A Product Line of Diodes Incorporated

SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	8.000000 MHz
PRODUCT TYPE	**TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL**
SPEC. NO. (P/N)	FL0800031Q
CUSTOMER P/N	
ISSUE DATE	March 11, 2019
VERSION	A

APPROVED	PREPARED	QA
Brenda	Claire	Jenny Yang

Diodes Incorporated

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***Pb-free**
***RoHS Compliant**
***HF-Halogen Free**
***REACH Compliant**
***AEC-Q200 Compliant**

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VERSION HISTORY

Version No.	Version Date	Description	Notes
A	Mar.11,2019	Initial Release	

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TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL

FL0800031Q

VER. A 11-Mar-19

ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	8.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	8	pF	
Calibration Tolerance	FL	±20	ppm	at 25°C±3°C
Operating Temperature Range	TR	-40 to +85	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±30	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	µW	
Maximum Drive Level		100	µW	
Equivalent Series Resistance	ESR	500	Ω	Max
Shunt Capacitance	C0	5	pF	Max
Aging at 25°C		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	MΩ	Min

※ This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).

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AEC-Q200 RELIABILITY TEST SPECIFICATIONS:

1. Initial

1.1 Physical Dimensions: JESD22, Method JB1-100

1.2 External Visual: MIL-STD-883, Method 2009

1.3 Freq. Vs. Temperature: Per Specification/Datasheet

2. Mechanical

2.1 Mechanical Shock: MIL-STD-202 Method 213

2.2 Vibration: MIL-STD-202 Method 204

2.3 Solderability: J-STD-002

2.4 Board Flex: AEC Q200-005

2.5 Terminal Strength (SMD): AEC Q200-006

3.Environmental

3.1 Temp Cycle: JESD22, Method JA-104

3.2 Resistance to Solder Heat: MIL-STD-202 Method 210

3.3 High Temperature Operating Life: MIL-STD-202, Method 108

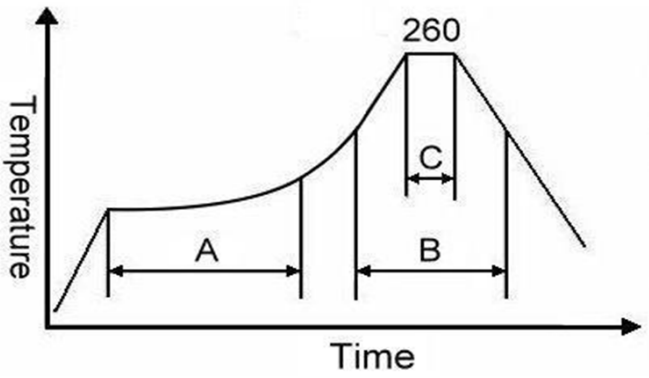
3.4 High Temp Exposure: MIL-STD-202, Method 108

3.5 High Temp & High Humidity: MIL-STD-202, Method 103

3.6 Thermal Shock: MIL-STD-202, Method 107

SUGGESTED IR REFLOW PROFILE

*As per IPC-JEDEC J-STD-020D

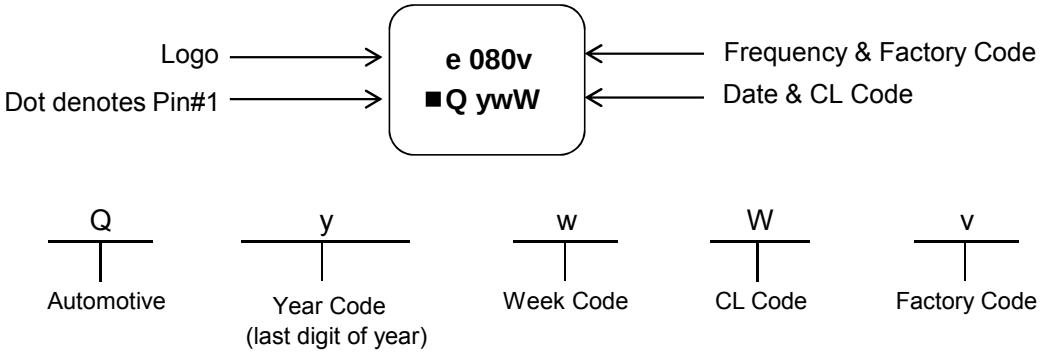


Note:

	Stage	Temperature	Time
A	Preheat	150~200°C	60~120 Sec
B	Primary Heat	217°C	60~150 Sec
C	Peak	260°C	10 Sec

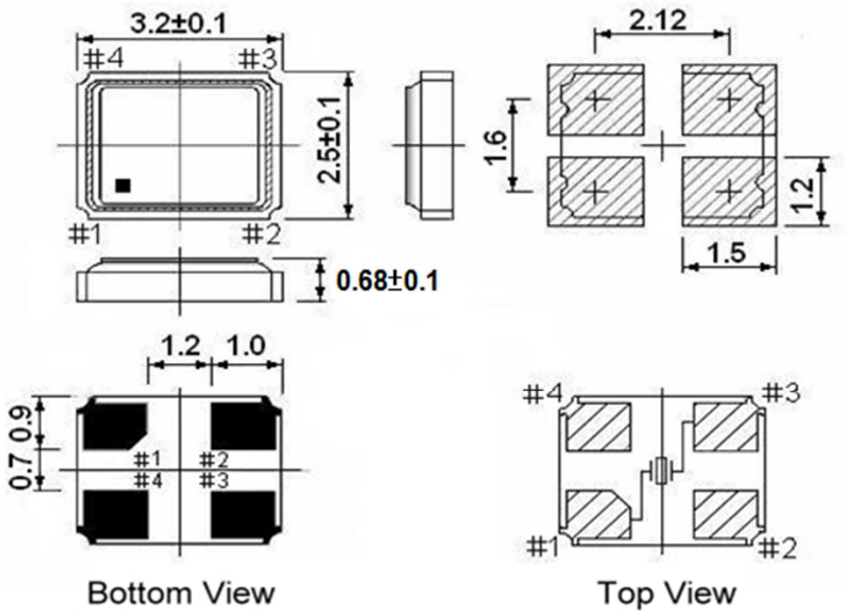
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MARKING



MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)

Recommended Land Pattern



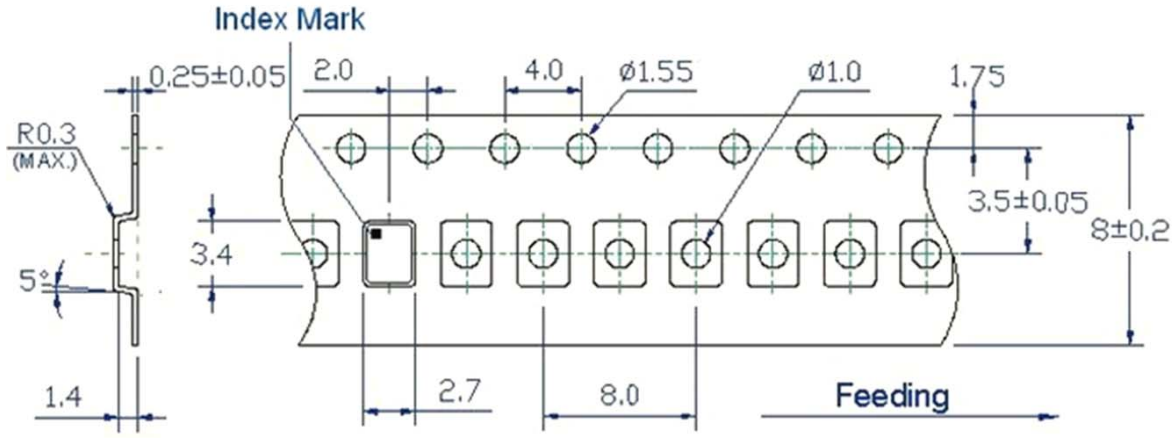
** Recommended - Pin 1 & 3 : CRYSTAL
Pin 2 & 4 : GND

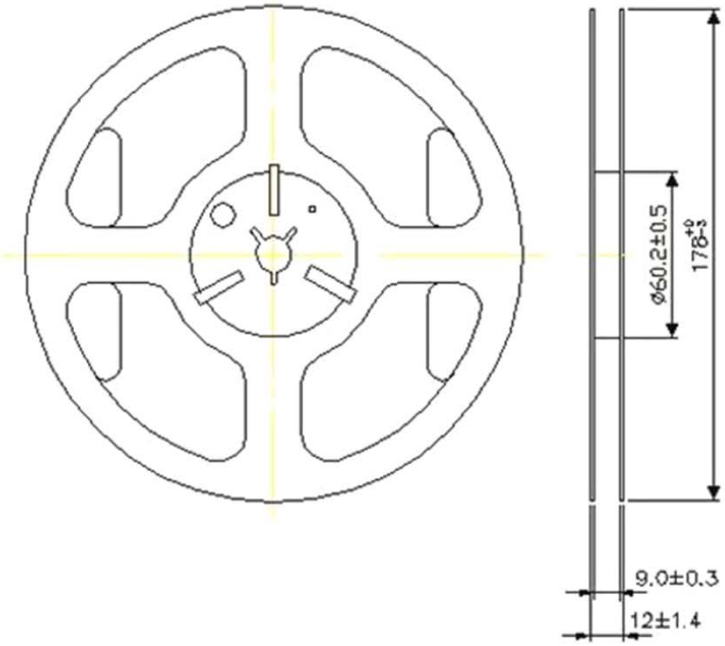
Notes:

1. Package drawings are for reference only, and the appearances of objects may vary.
   Actual packages are based on the real product.
2. The marking dot denotes Pin#1.
3. The position and shape of the chamfer pin may vary and are based on the real product.

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Tape & Reel



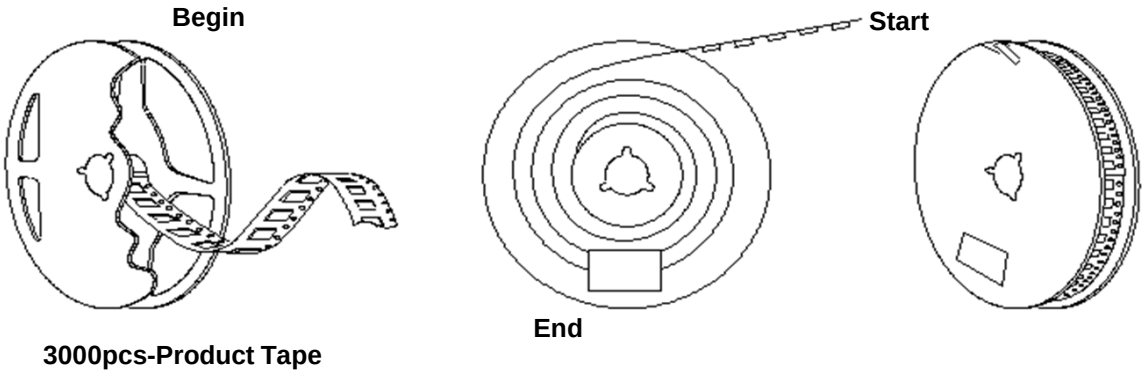


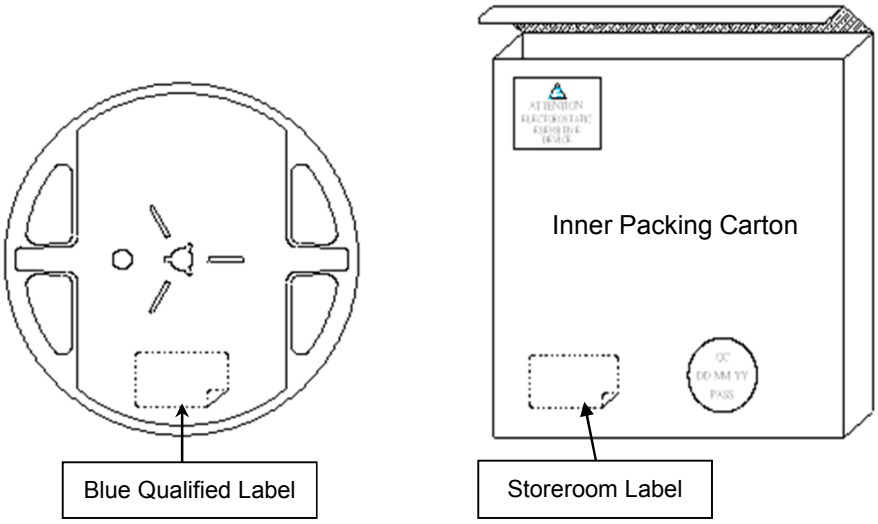
1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.

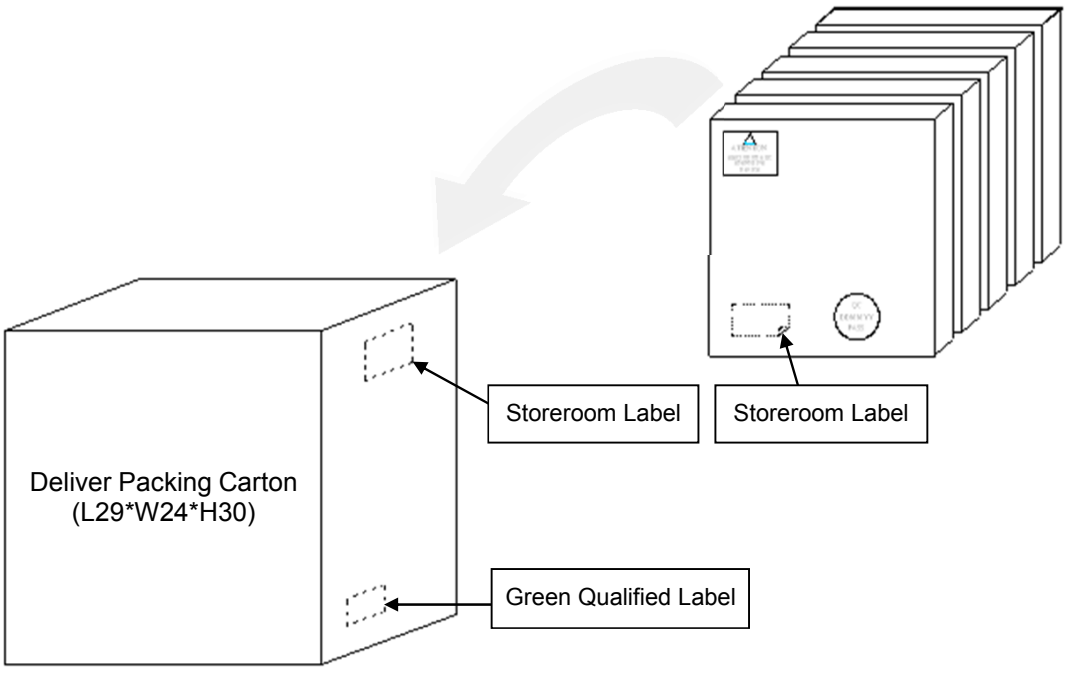
2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

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PACKING







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